

MPSA44

Preferred Device

High Voltage Transistor NPN Silicon

Features

- Pb-Free Packages are Available*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V_{CEO}	400	Vdc
Collector-Base Voltage	V_{CBO}	500	Vdc
Emitter-Base Voltage	V_{EBO}	6.0	Vdc
Collector Current - Continuous	I_C	300	mAdc
Total Device Dissipation @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	625 5.0	mW mW/ $^\circ\text{C}$
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D	1.5 12	W mW/ $^\circ\text{C}$
Operating and Storage Junction Temperature Range	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$

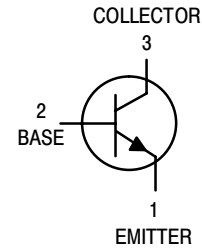
THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	200	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	83.3	$^\circ\text{C}/\text{W}$

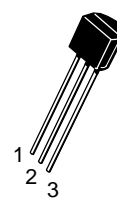
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



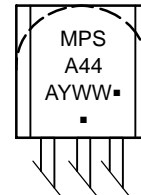
ON Semiconductor®



MARKING DIAGRAM



TO-92
(TO-226AA)
CASE 29-11
STYLE 1



A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb-Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector–Emitter Breakdown Voltage (Note 1) (I _C = 1.0 mA _{dc} , I _B = 0)	V _{(BR)CEO}	400	–	V _{dc}
Collector–Emitter Breakdown Voltage (I _C = 100 μA _{dc} , V _{BE} = 0)	V _{(BR)CES}	500	–	V _{dc}
Collector–Base Breakdown Voltage (I _C = 100 μA _{dc} , I _E = 0)	V _{(BR)CBO}	500	–	V _{dc}
Emitter–Base Breakdown Voltage (I _E = 10 μA _{dc} , I _C = 0)	V _{(BR)EBO}	6.0	–	V _{dc}
Collector Cutoff Current (V _{CB} = 400 V _{dc} , I _E = 0)	I _{CBO}	–	0.1	μA _{dc}
Collector Cutoff Current (V _{CE} = 400 V _{dc} , V _{BE} = 0)	I _{CES}	–	500	nA _{dc}
Emitter Cutoff Current (V _{EB} = 4.0 V _{dc} , I _C = 0)	I _{EBO}	–	0.1	μA _{dc}

ON CHARACTERISTICS (Note 1)

DC Current Gain (Note 1) (I _C = 1.0 mA _{dc} , V _{CE} = 10 V _{dc}) (I _C = 10 mA _{dc} , V _{CE} = 10 V _{dc}) (I _C = 50 mA _{dc} , V _{CE} = 10 V _{dc}) (I _C = 100 mA _{dc} , V _{CE} = 10 V _{dc})	h _{FE}	40 50 45 40	– 200 – –	–
Collector–Emitter Saturation Voltage (Note 1) (I _C = 1.0 mA _{dc} , I _B = 0.1 mA _{dc}) (I _C = 10 mA _{dc} , I _B = 1.0 mA _{dc}) (I _C = 50 mA _{dc} , I _B = 5.0 mA _{dc})	V _{CE(sat)}	– – –	0.4 0.5 0.75	V _{dc}
Base–Emitter Saturation Voltage (I _C = 10 mA _{dc} , I _B = 1.0 mA _{dc})	V _{BE(sat)}	–	0.75	V _{dc}

SMALL–SIGNAL CHARACTERISTICS

Output Capacitance (V _{CB} = 20 V _{dc} , I _E = 0, f = 1.0 MHz)	C _{obo}	–	7.0	pF
Input Capacitance (V _{EB} = 0.5 V _{dc} , I _C = 0, f = 1.0 MHz)	C _{ibo}	–	130	pF
Small–Signal Current Gain (I _C = 10 mA _{dc} , V _{CE} = 10 V _{dc} , f = 20 MHz)	h _{fe}	1.0	–	–

1. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

ORDERING INFORMATION

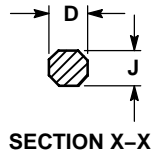
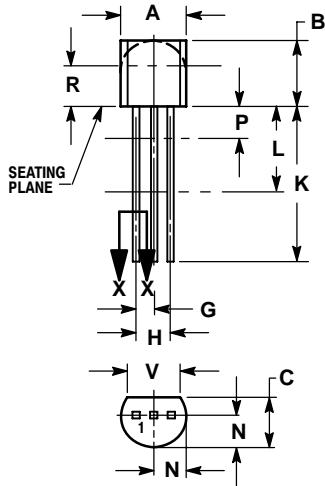
Device	Package	Shipping†
MPSA44	TO–92	5000 Units / Box
MPSA44G	TO–92 (Pb–Free)	5000 Units / Box
MPSA44RL1	TO–92	2000 / Tape & Reel
MPSA44RL1G	TO–92 (Pb–Free)	2000 / Tape & Reel
MPSA44RLRA	TO–92	2000 / Tape & Reel
MPSA44RLRAG	TO–92 (Pb–Free)	2000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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PACKAGE DIMENSIONS

TO-92 (TO-226)
CASE 29-11
ISSUE AL



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.175	0.205	4.45	5.20
B	0.170	0.210	4.32	5.33
C	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
H	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500	---	12.70	---
L	0.250	---	6.35	---
N	0.080	0.105	2.04	2.66
P	---	0.100	---	2.54
R	0.115	---	2.93	---
V	0.135	---	3.43	---

STYLE 1:

- PIN 1. EMITTER
2. BASE
3. COLLECTOR